





IFN3993/A, IFN3994/A P-Channel JFET

Support

Features

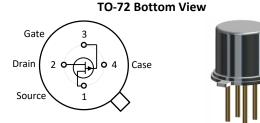
- InterFET P0099F Geometry
- Typical Noise: 8 nV/VHz
- Fast Switching
- Replacement for 2N3993,4 Parts
- RoHS Compliant
- SMT, TH, and Bare Die Package options.

Applications

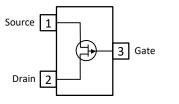
- Choppers
- High Speed Commutators

Description

The 25V InterFET IFN3993/A and IFN3994/A are targeted for choppers and high speed commutator designs. The on resistance is typically less than 100 Ohms at room temperatures. The TO-72 package is hermetically sealed and suitable for military applications.

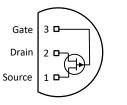














Product Summary (Highlighted values = A variant)

| Parameters | | IFN3993/A Min | IFN3994/A Min | Unit |
|----------------------|------------------------------------|---------------|---------------|------|
| BV _{GSS} | Gate to Source Breakdown Voltage | 25 | 25 | V |
| I _{DSS} | Drain to Source Saturation Current | -10 | -2 | mA |
| V _{GS(off)} | Gate to Source Cutoff Voltage | 4 | 1 | V |
| GFS | Forward Transconductoria | 6 | 4 | |
| | Forward Transconductance | 7 | 5 | μS |

Ordering Information Custom Part and Binning Options Available

| Part Number | Description | Case | Packaging |
|--------------------------|--|-------|----------------------|
| IFN3993; IFN3994 | | | |
| IFN3993A; IFN3994A | Through-Hole | TO-72 | Bulk |
| PN3993; PN3994 | | | |
| PN3993A; PN3994A | Through-Hole | TO-92 | Bulk |
| SMP3993; SMP3994 | | | |
| SMP3993A; SMP3994A | Surface Mount | SOT23 | Bulk |
| SMP3993TR; SMP3994TR | 7" Tape and Reel: Max 3,000 Pieces | | Minimum 1,000 Pieces |
| SMP3993ATR; SMP3994ATR | 13" Tape and Reel: Max 9,000 Pieces | SOT23 | Tape and Reel |
| IFN3993COT; IFN3994COT | | | |
| IFN3993ACOT; IFN3994ACOT | Chip Orientated Tray (COT Waffle Pack) | СОТ | 400/Waffle Pack |
| IFN3993CFT; IFN3994CFT | | | |
| IFN3993ACFT; IFN3994ACFT | Chip Face-up Tray (CFT Waffle Pack) | CFT | 400/Waffle Pack |



Disclaimer: It is the Buyers responsibility for designing, validating and testing the end application under all field use cases and extreme use conditions. Guaranteeing the application meets required standards, regulatory compliance, and all safety and security requirements is the responsibility of the Buyer. These resources are subject to change without notice.







Support

Electrical Characteristics

Maximum Ratings (@ T_A = 25°C, Unless otherwise specified)

| | Parameters | Value | Unit | |
|------------------|--|------------|-------|--|
| VRGS | Reverse Gate Source and Gate Drain Voltage | 25 | V | |
| I_{FG} | Continuous Forward Gate Current | -10 | mA | |
| PD | Continuous Device Power Dissipation | 300 | mW | |
| Р | Power Derating | 2.4 | mW/°C | |
| Τı | Operating Junction Temperature | -55 to 125 | °C | |
| T _{STG} | Storage Temperature | -65 to 150 | °C | |

Static Characteristics (@ TA = 25°C, Unless otherwise specified, Highlighted values = A variant)

| | | | IFN3993/A | | IFN3994/A | | |
|---------------------|---------------------------------------|---|-----------|------------|-----------|------------|----------|
| | Parameters | Conditions | Min | Max | Min | Max | Unit |
| V(BR)GSS | Gate to Source Breakdown Voltage | $V_{DS} = 0V$, $I_G = 1\mu A$ | 25 | | 25 | | V |
| Vgs(off) | Gate to Source Cutoff Voltage | $V_{DS} = -10V, I_{D} = -1\mu A$ | 4 | 9.5 | 1 | 5.5 | v |
| I _{DSS} | Drain to Source Saturation Current | V _{GS} = 0V, V _{DS} = -10V (Pulsed) | -10 | | -2 | | mA |
| I _{DGO} | Drain Reverse Current | V _{GS} = -15V, I _S = 0A, T _A = 25°C V _{GS} = -15V, I _S = 0A, T _A = 150°C | | -1.2 | | -1.2 | nA μA |
| I _{D(OFF)} | Drain Cutoff Current | V _{DS} = -10V, V _{GS} = 10V, T _A = 25°C V _{DS} = -10V, V _{GS} = 10V, T _A = 150°C | | -1.2 -1 | | -1.2 -1 | nA μA |

Dynamic Characteristics (@ TA = 25°C, Unless otherwise specified, Highlighted values = A variant)

| | | | IFN3993/A | | IFN3994/A | | |
|---------|----------------------------------|---|-----------|-----|-----------|-----|------|
| | Parameters | Conditions | Min | Max | Min | Max | Unit |
| GFS | Forward | (1 - 10)(1)(1 - 0)(1 - 1)(1) | 6 | 12 | 4 | 10 | mS |
| | Transconductance | $V_{DS} = -10V, V_{GS} = 0V, f = 1kHz$ | 7 | 12 | 5 | 10 | 1115 |
| Rds(on) | Drain to Source ON Resistance | V_{GS} = 0V, I _D = 0A, f = 1kHz | | 150 | | 300 | Ω |
| Ciss | Input Canaditance | $V_{DS} = -10V$, $V_{GS} = 0V$, f = 1MHz | | 16 | | 16 | |
| | Input Capacitance | $v_{DS} = -10v$, $v_{GS} = 0v$, $1 = 110Hz$ | | 12 | | 12 | рF |
| Crss | Reverse Transfer | V _{DS} = 0V, V _{GS} = 10V, f = 1MHz | | 4.5 | | 5 | pF |
| | Capacitance | | | 3 | | 3.5 | |



Technical

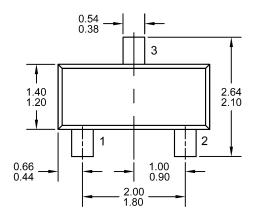
Support

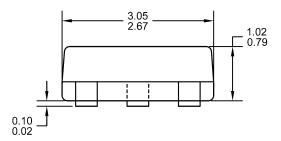
Order

Now

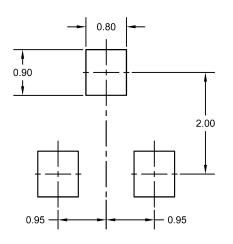
SOT23 (TO-236AB) Mechanical and Layout Data

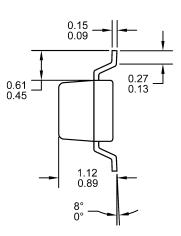
Package Outline Data





Suggested Pad Layout





- 1. All linear dimensions are in millimeters.
- 2. Package weight approximately 0.12 grams
- 3. Molded plastic case UL 94V-0 rated
- For Tape and Reel specifications refer to InterFET CTC-021 Tape and Reel Specification, Document number: IF39002
- 5. Bulk product is shipped in standard ESD shipping material
- 6. Refer to JEDEC standards for additional information.

- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided for reference only. A more robust pattern may be desired for wave soldering.



Technical Support

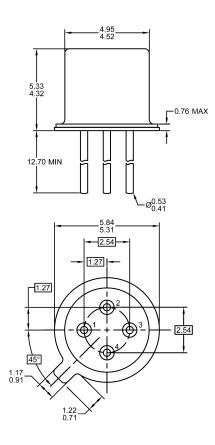
Order

Now

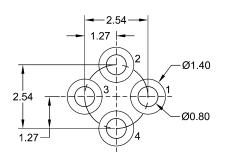


TO-72 Mechanical and Layout Data

Package Outline Data



Suggested Through-Hole Layout



- 1. All linear dimensions are in millimeters.
- 2. Four leaded device. Not all leads are shown in drawing views.
- 3. Package weight approximately 0.31 grams
- 4. Bulk product is shipped in standard ESD shipping material
- 5. Refer to JEDEC standards for additional information.

- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

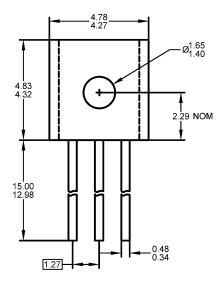


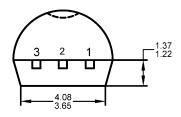
Technical Order Now

Support

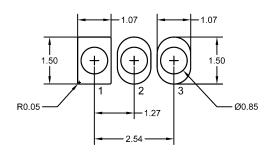
TO-92 Mechanical and Layout Data

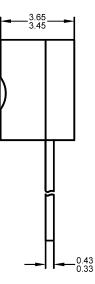
Package Outline Data





Suggested Through-Hole Layout





- All linear dimensions are in millimeters. 1.
- 2. Package weight approximately 0.19 grams
- 3. Molded plastic case UL 94V-0 rated
- 4. Bulk product is shipped in standard ESD shipping material
- 5. Refer to JEDEC standards for additional information.

- 1. All linear dimensions are in millimeters.
- 2. The suggested land pattern dimensions have been provided as a straight lead reference only. A more robust pattern may be desired for wave soldering and/or bent lead configurations.

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